CET6

COM. 0 Type 6 Evaluation Baseboard

Rev. C.0

MAIN

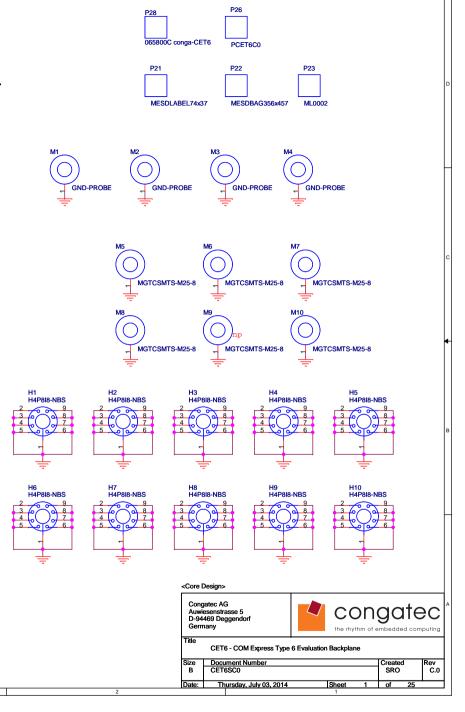
Content

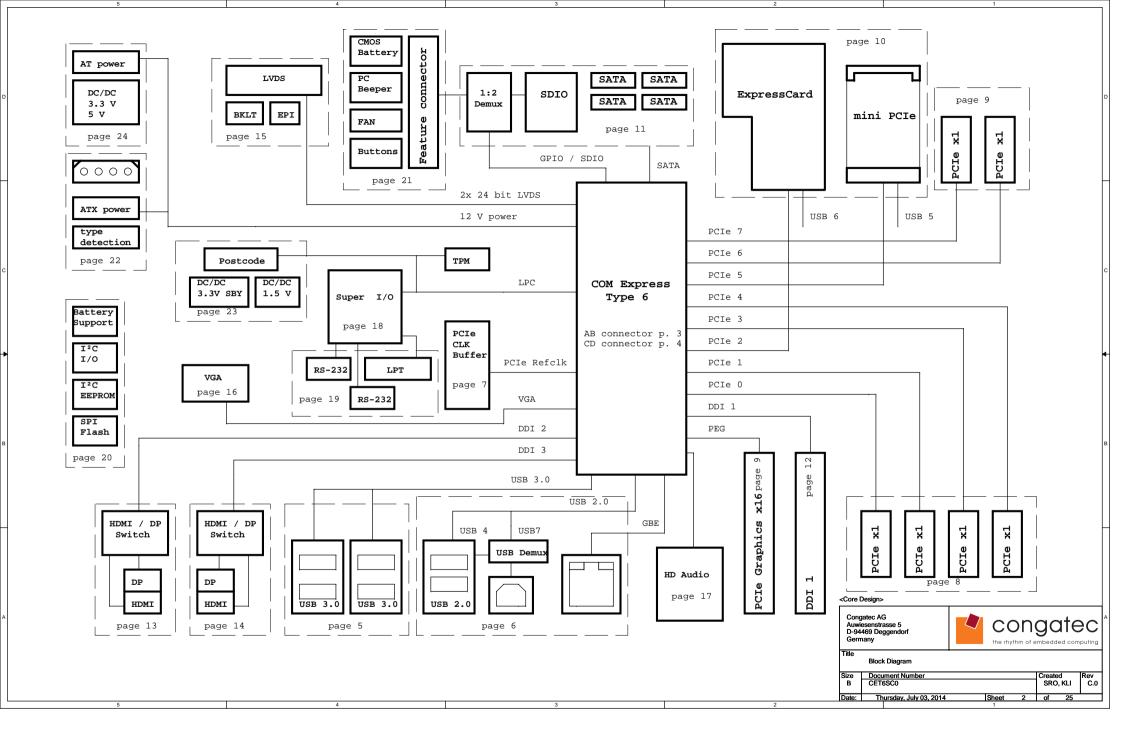
Page 1

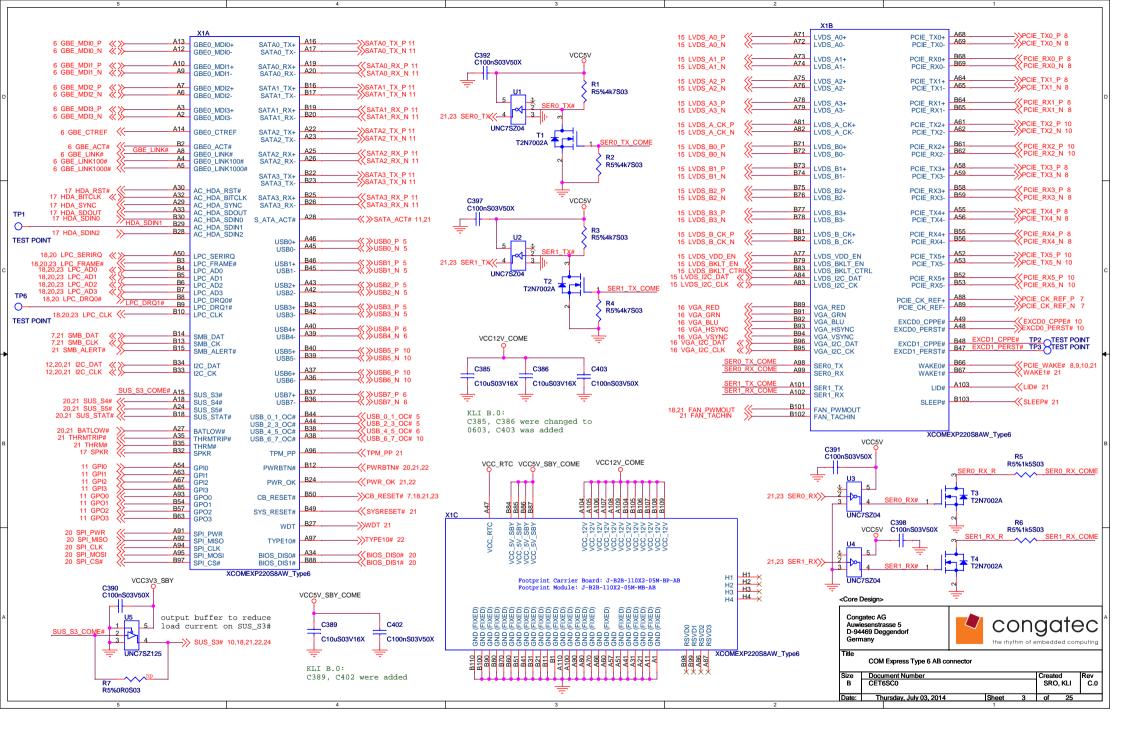
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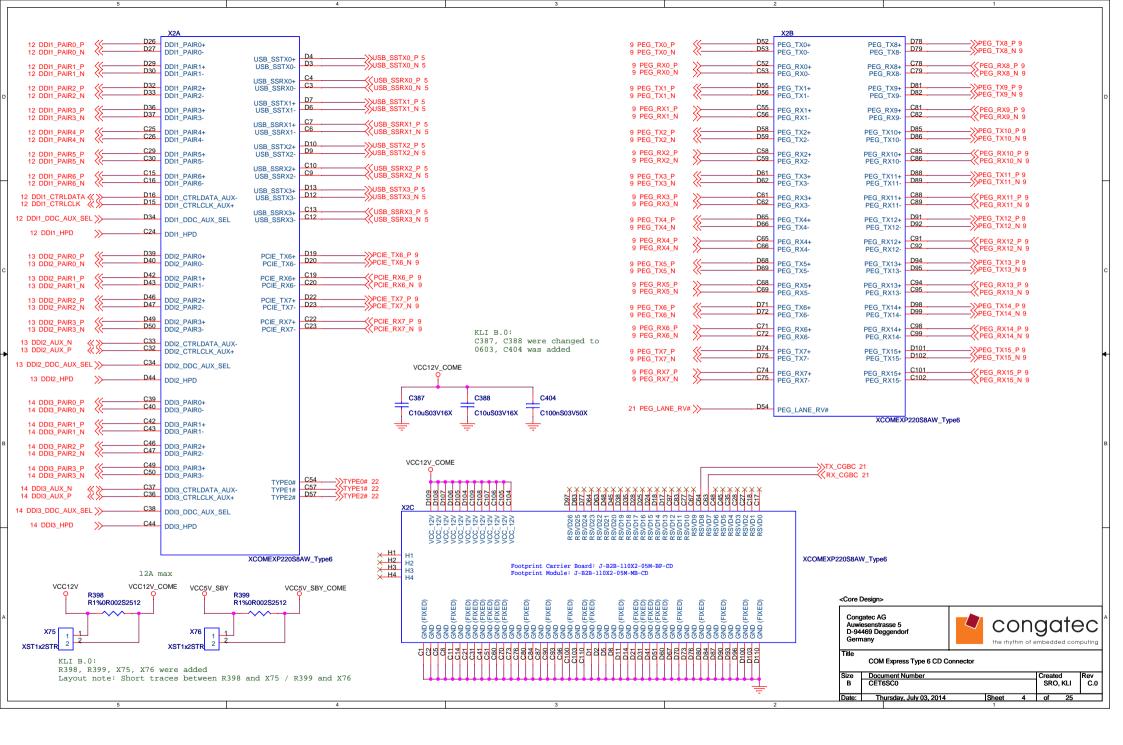
Variants

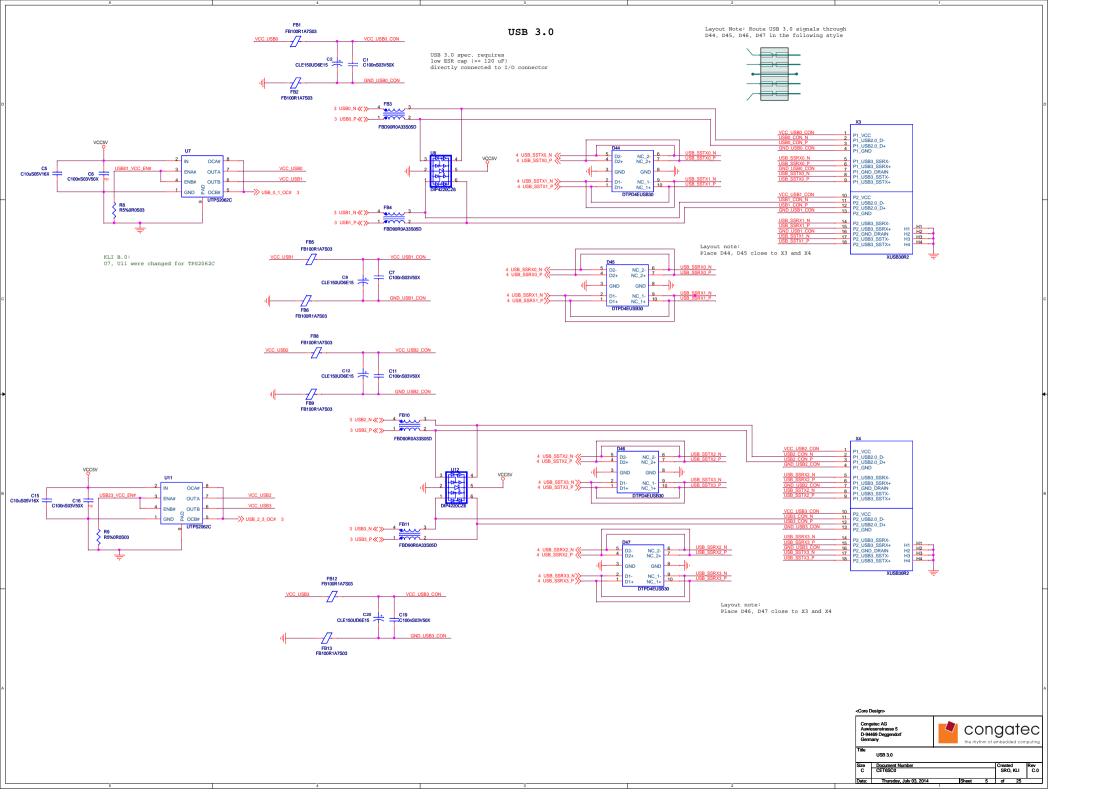
Base Standard w/ SuperIO W83627-DHG-P

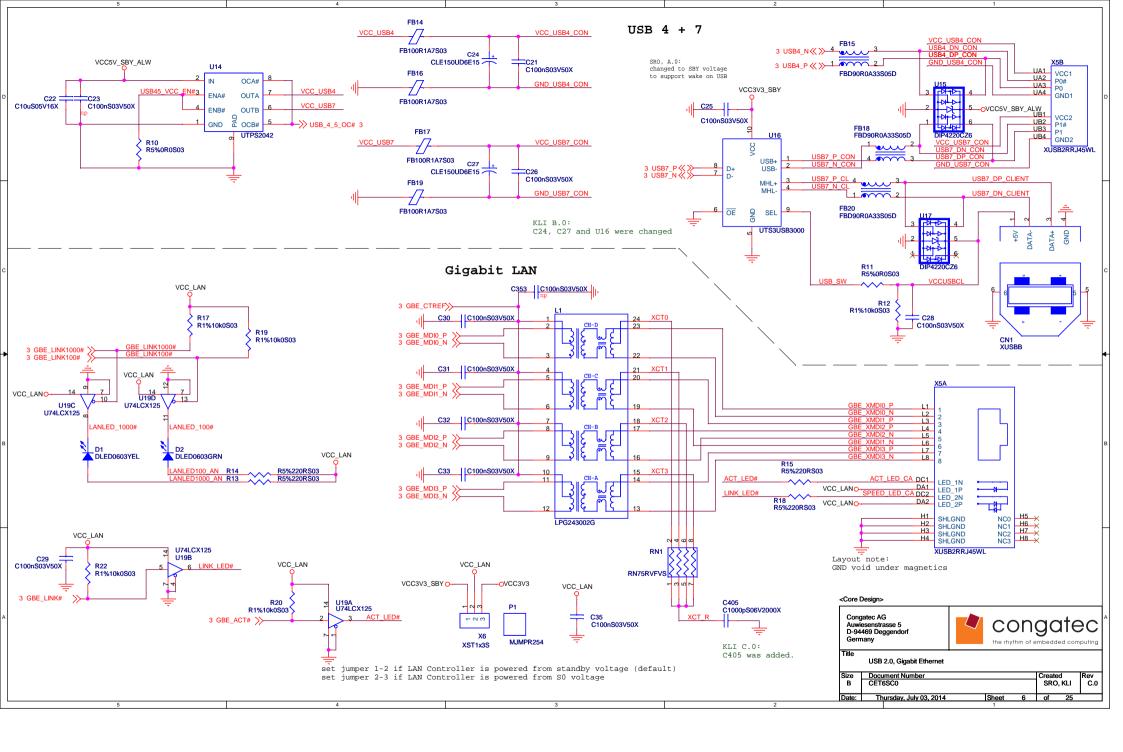


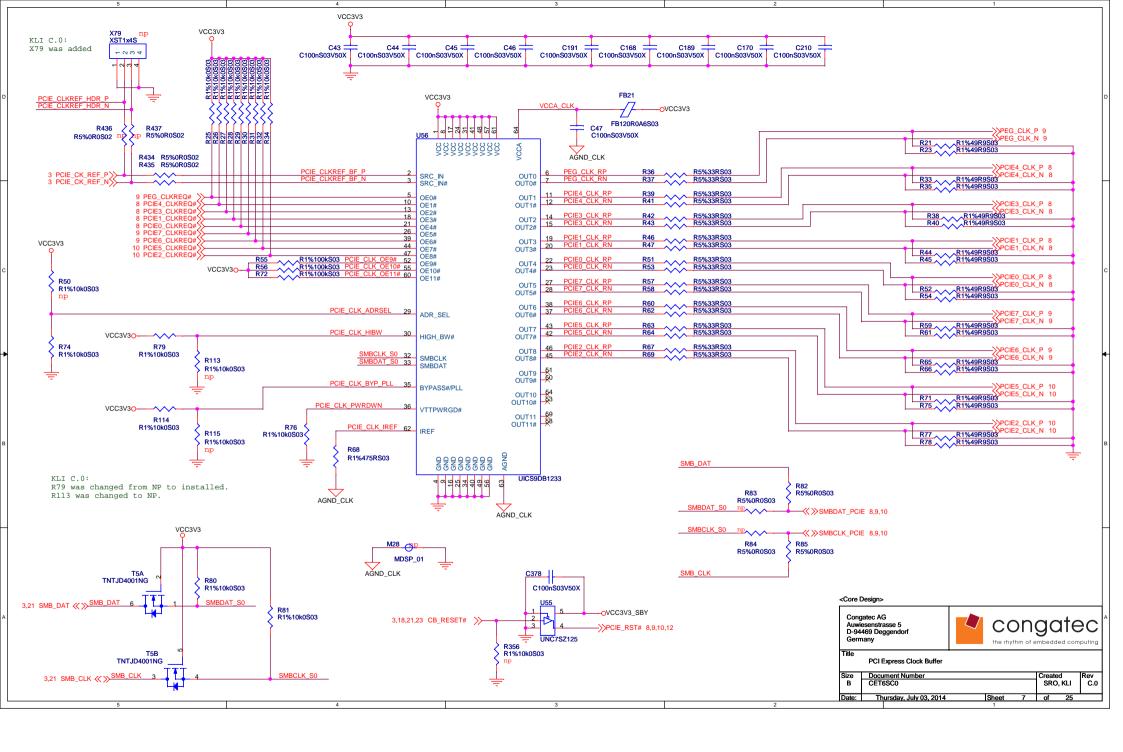


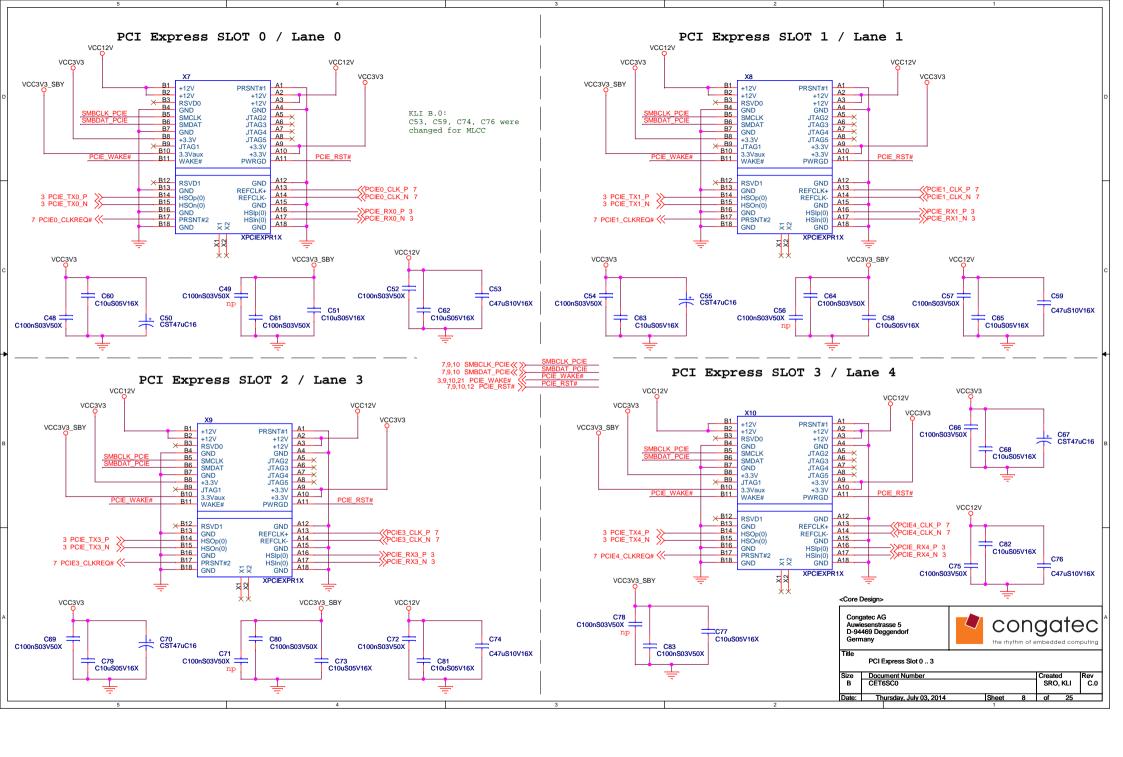


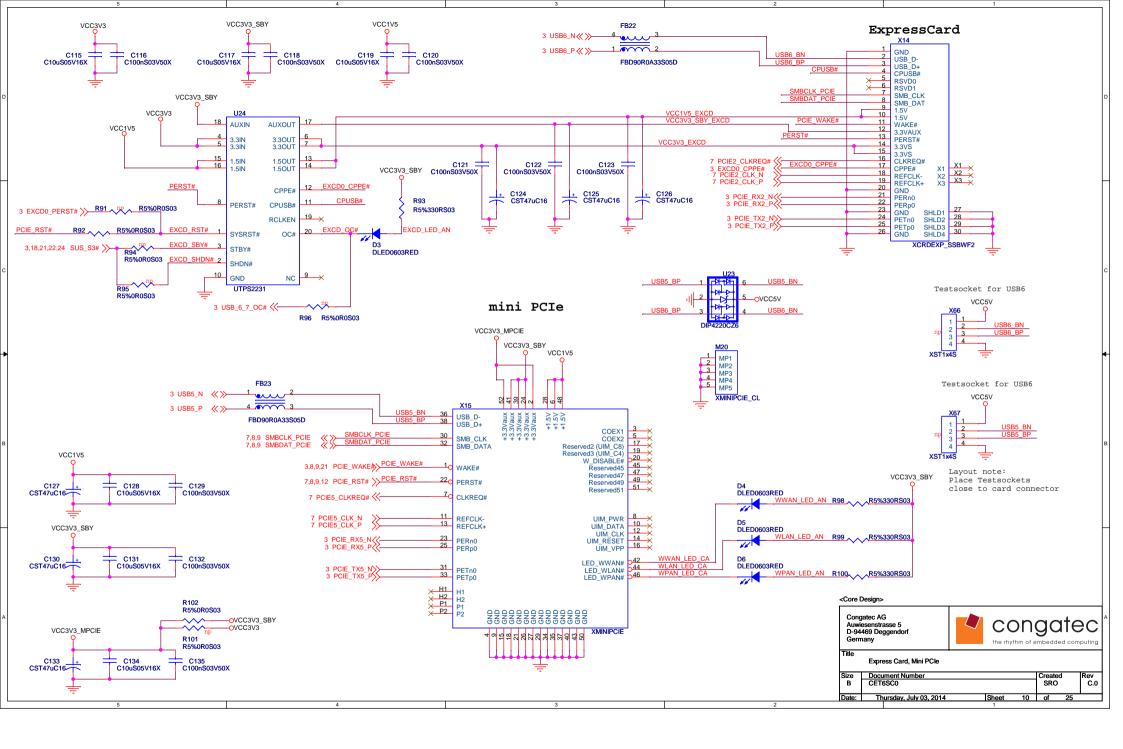


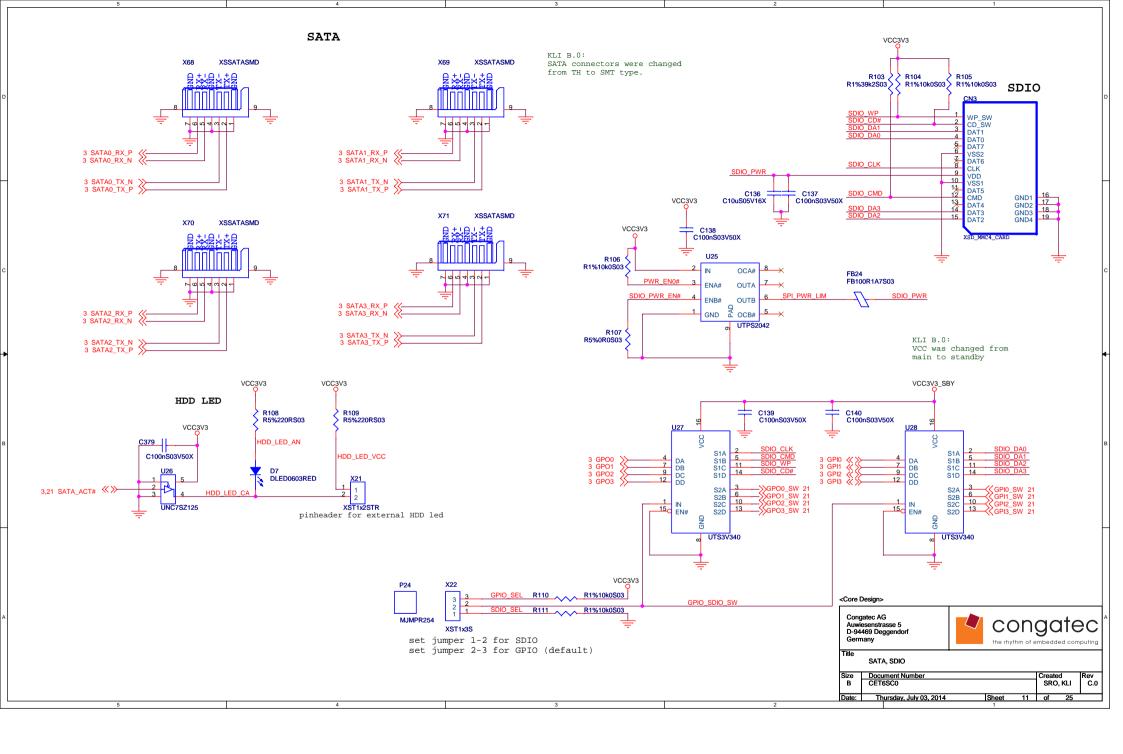


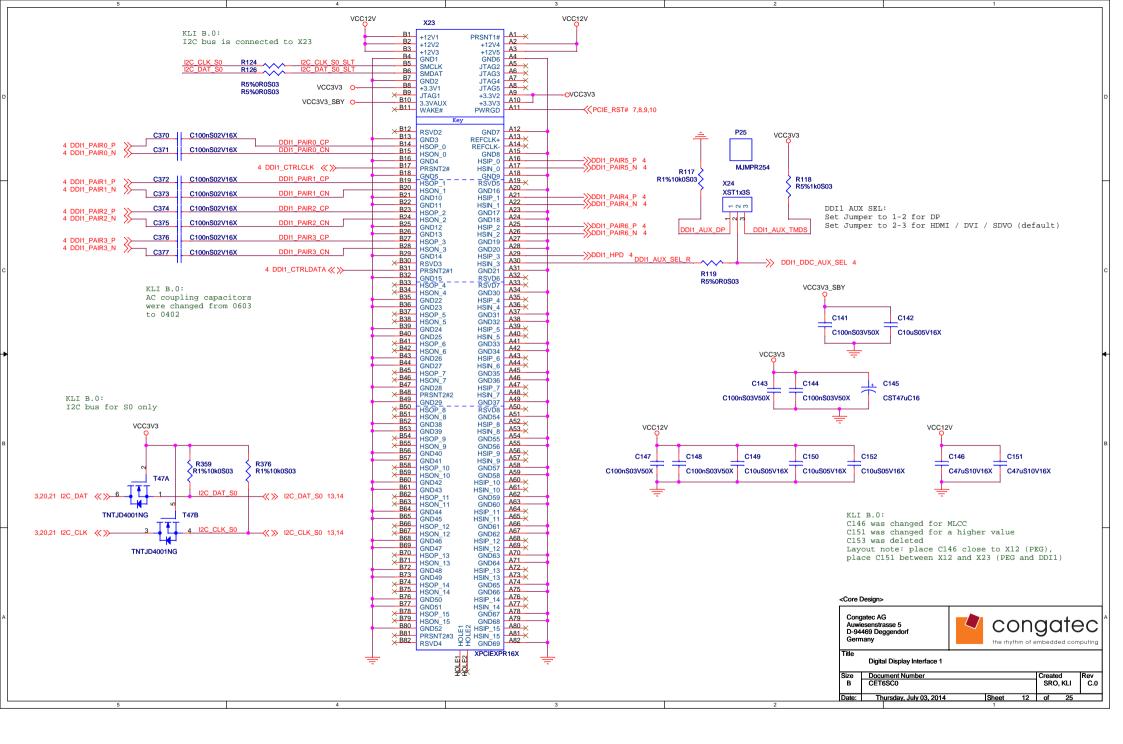


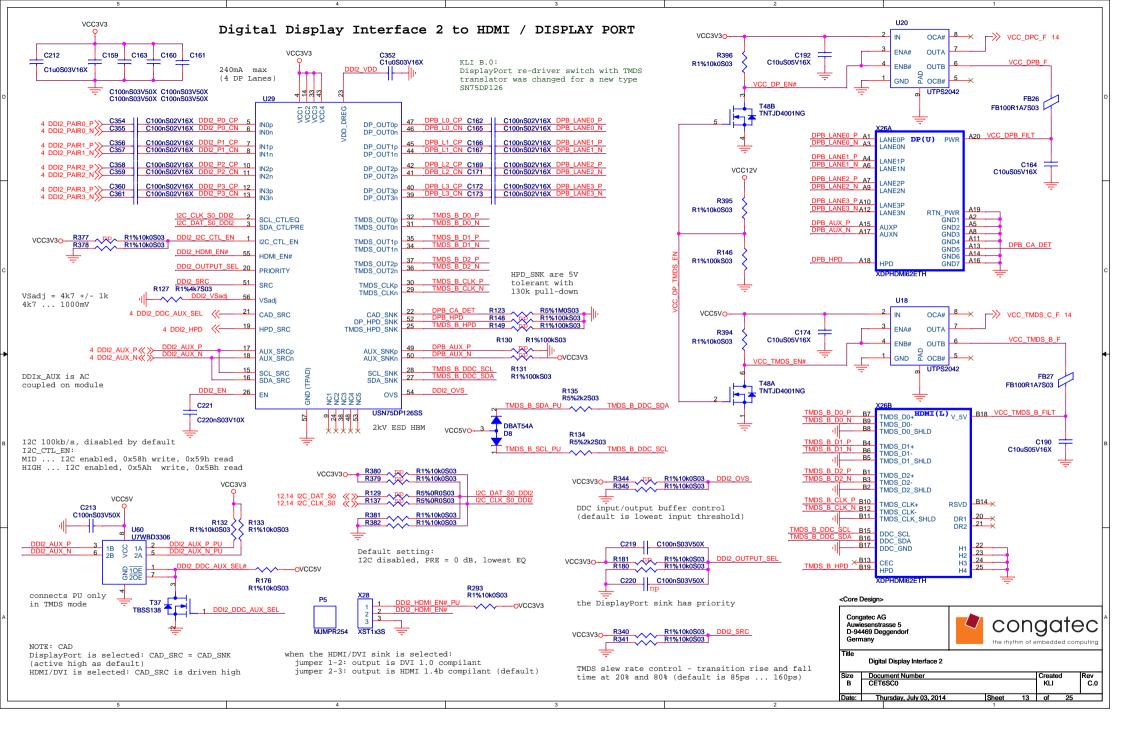


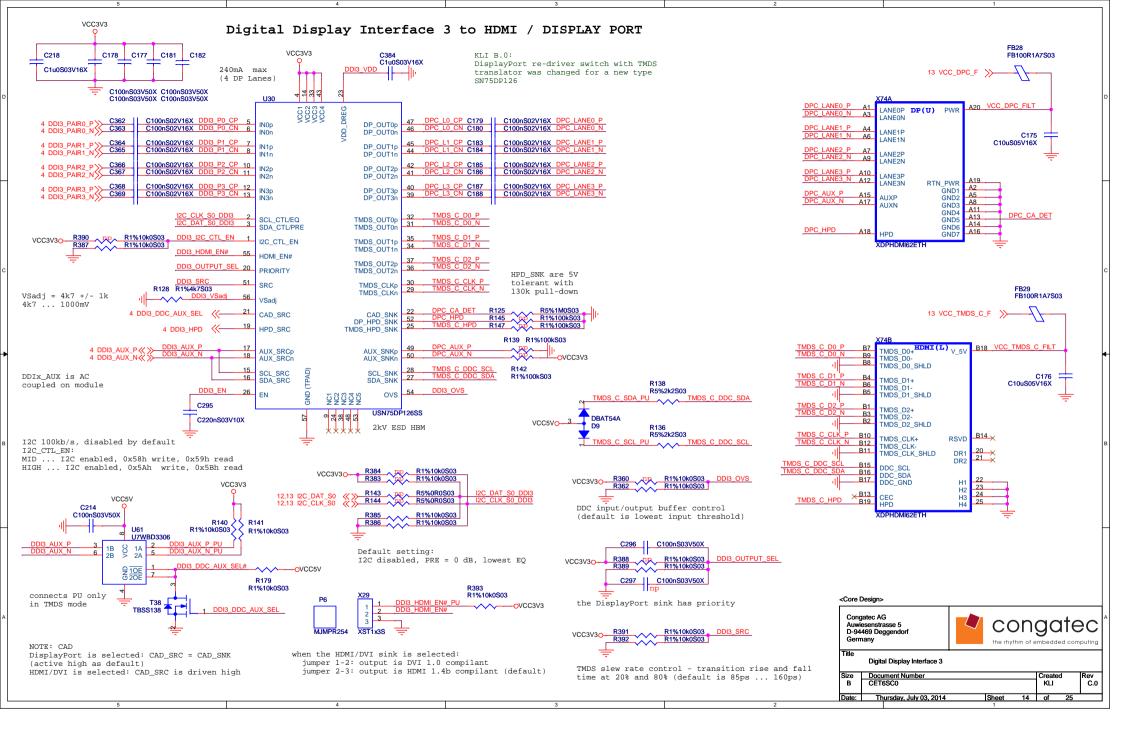


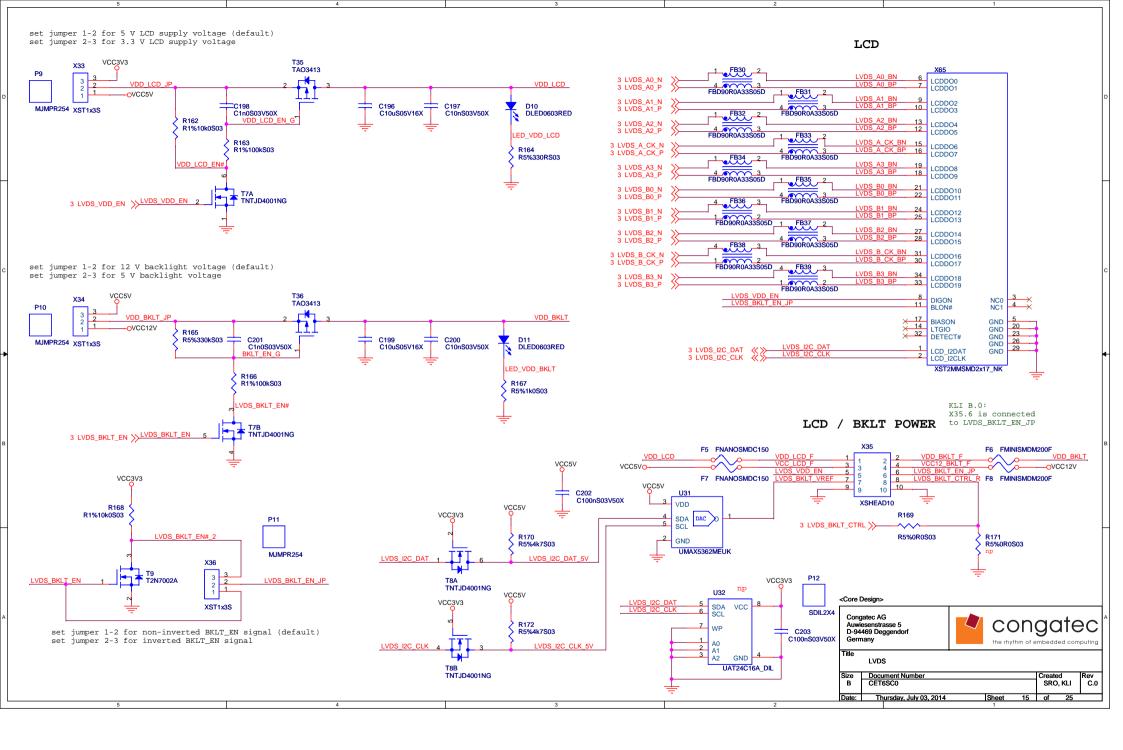


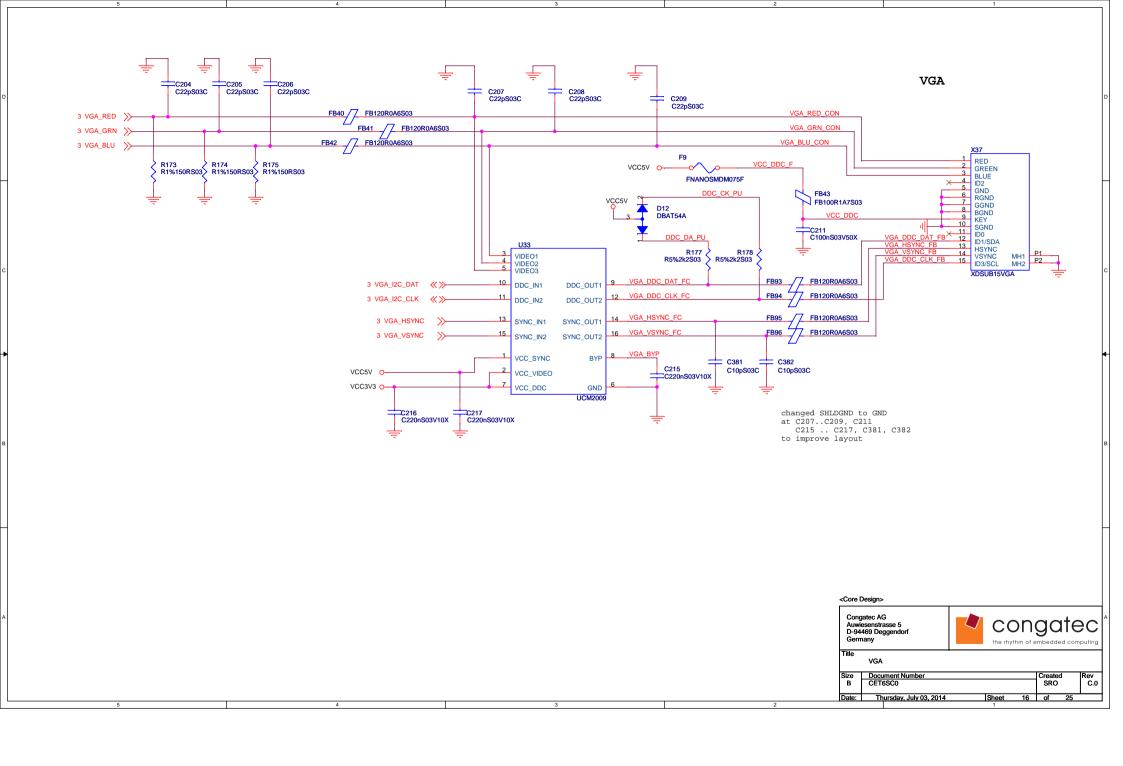


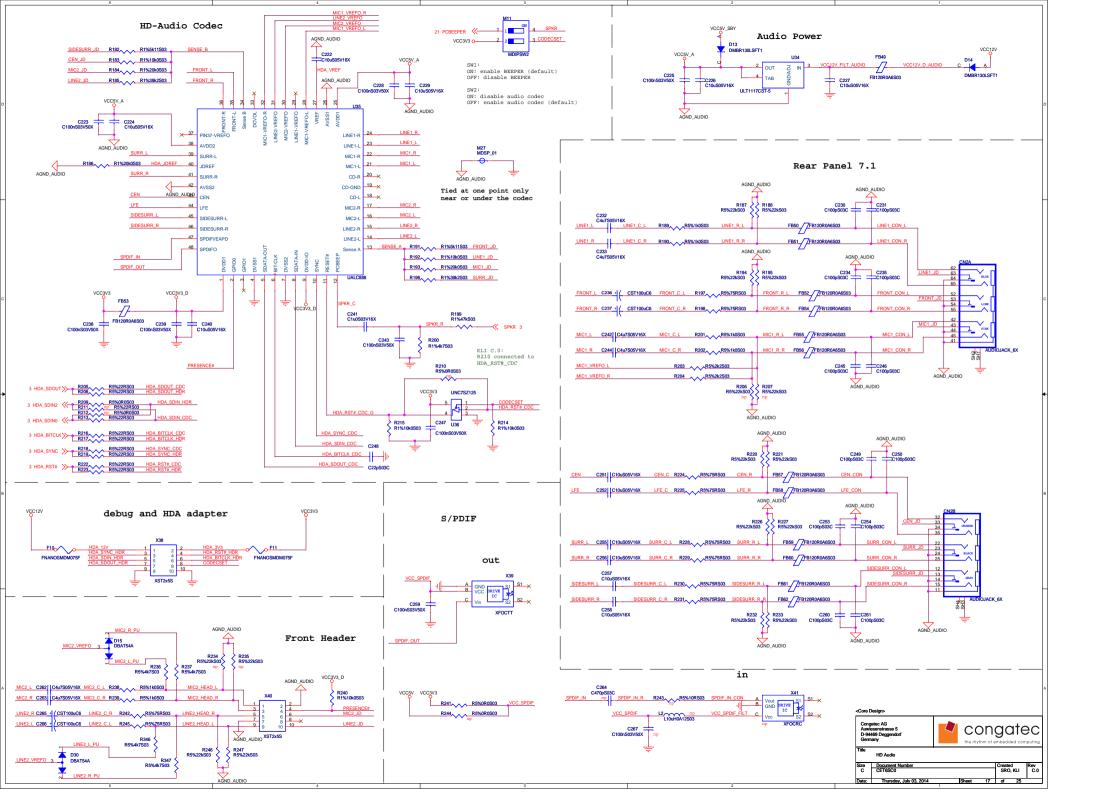


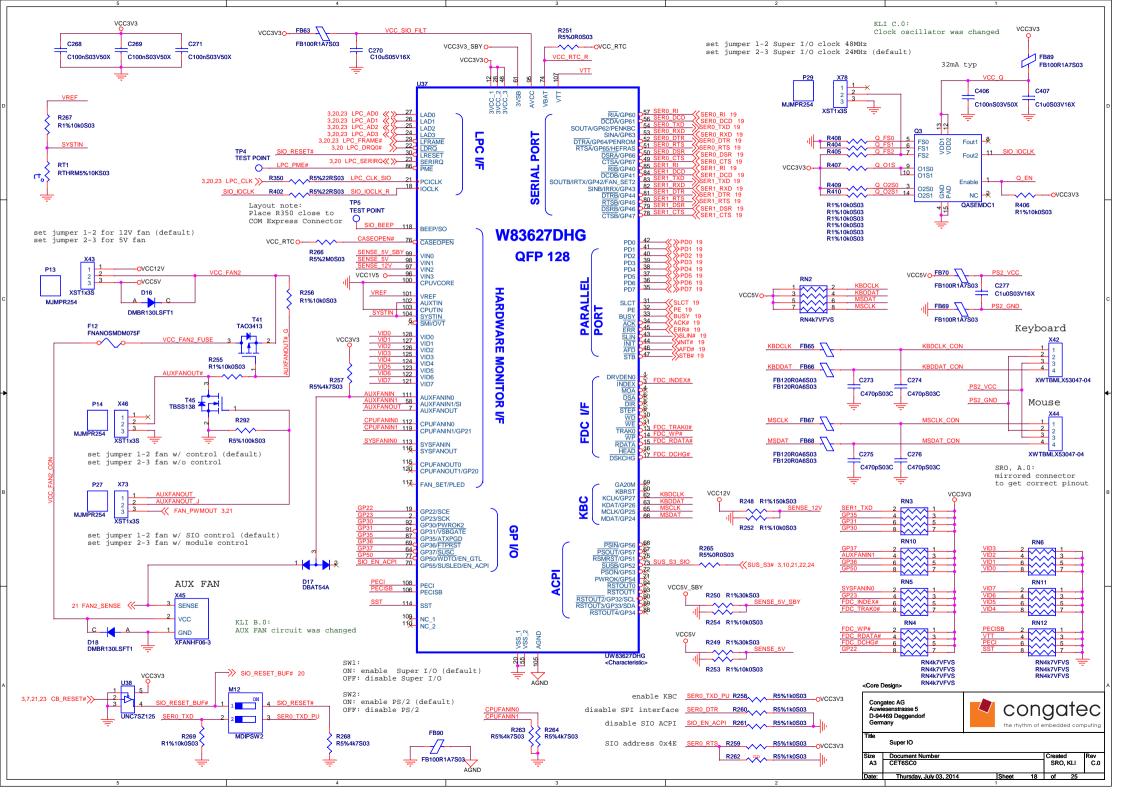


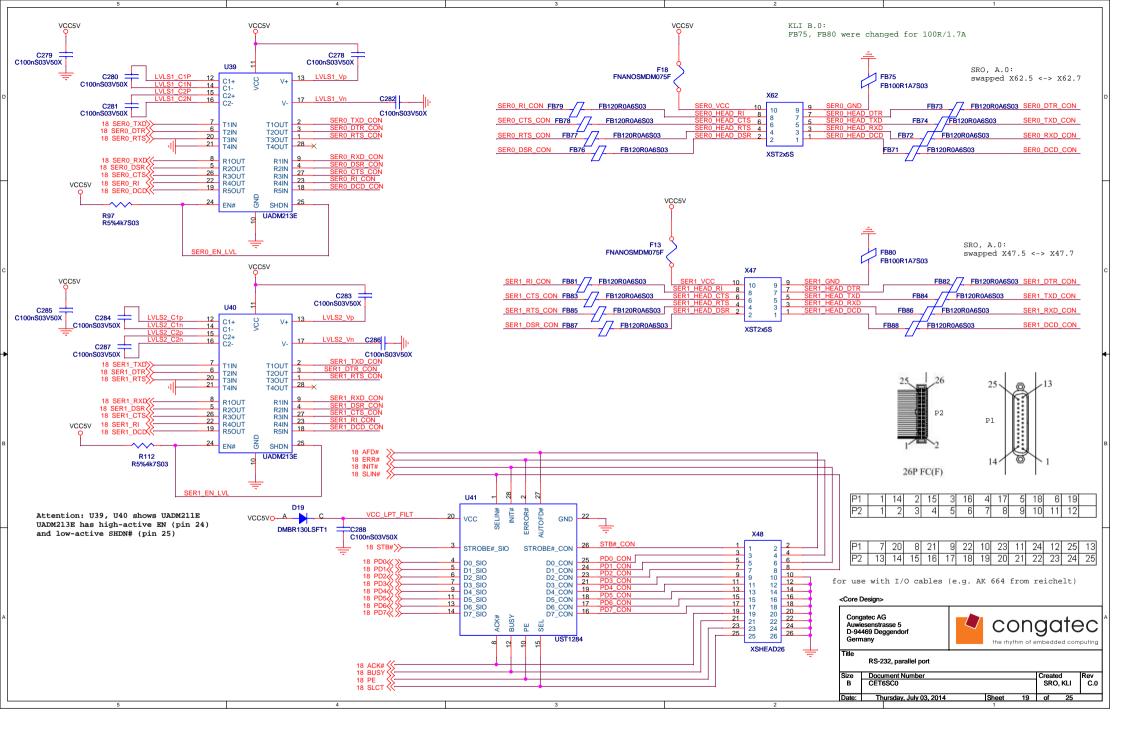


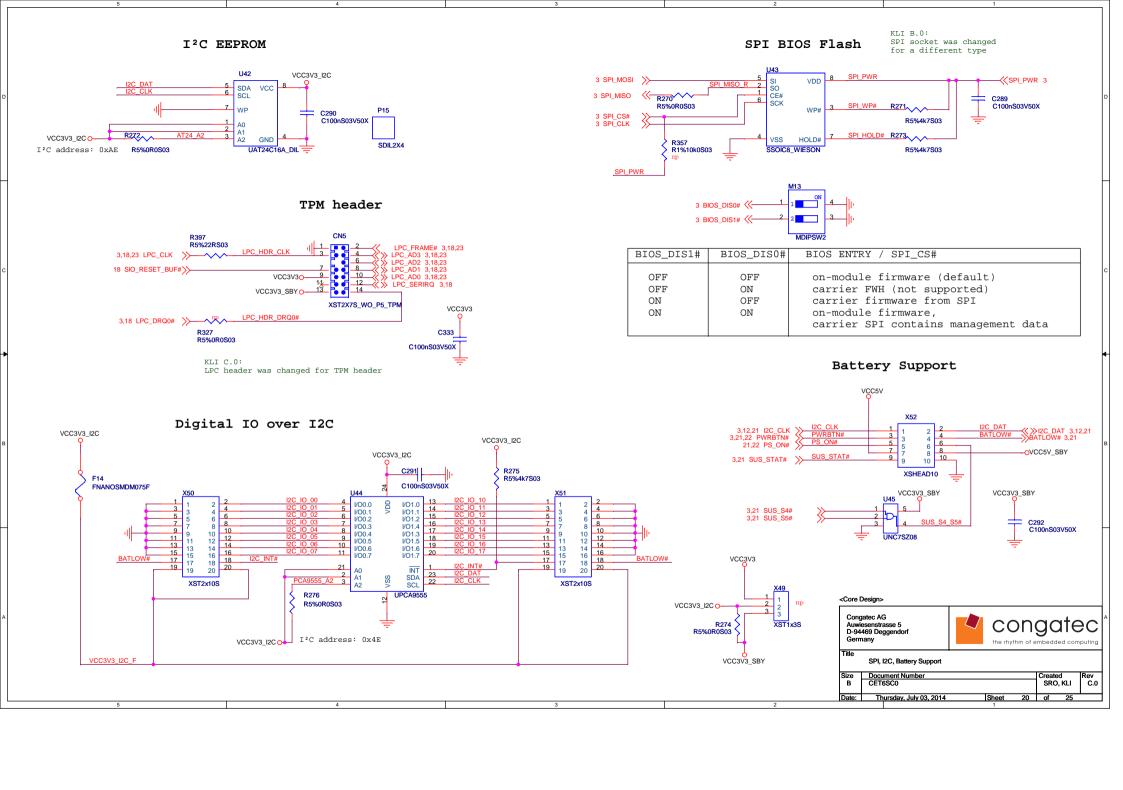


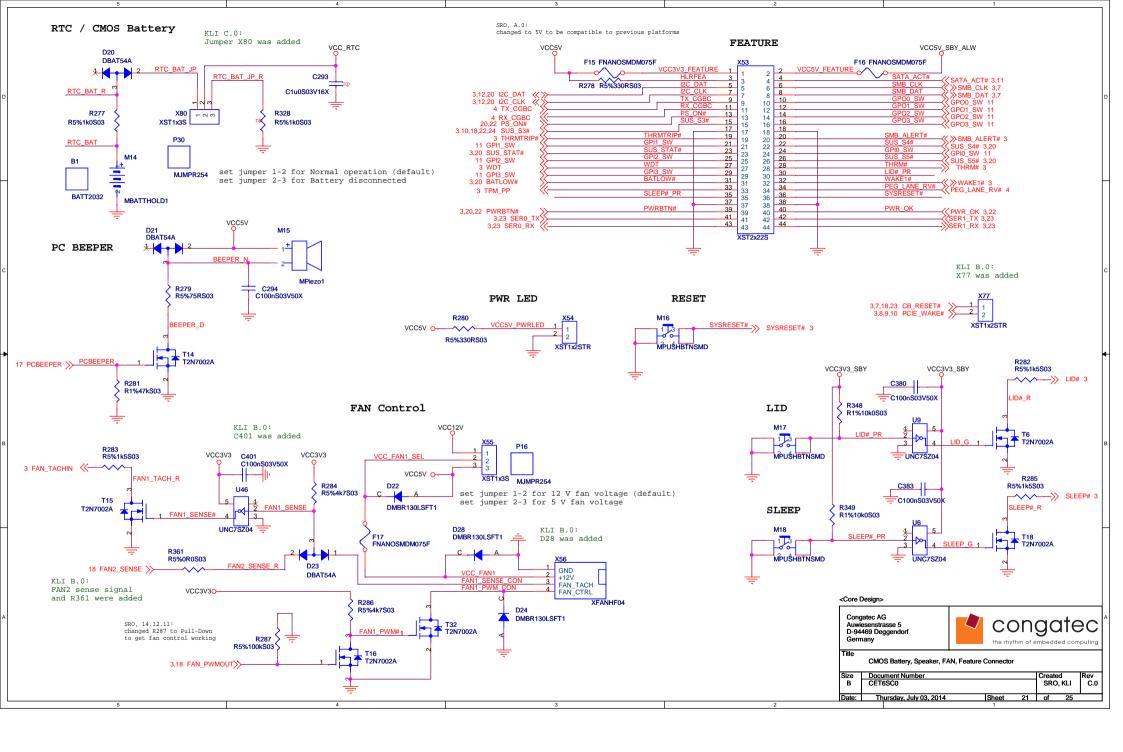


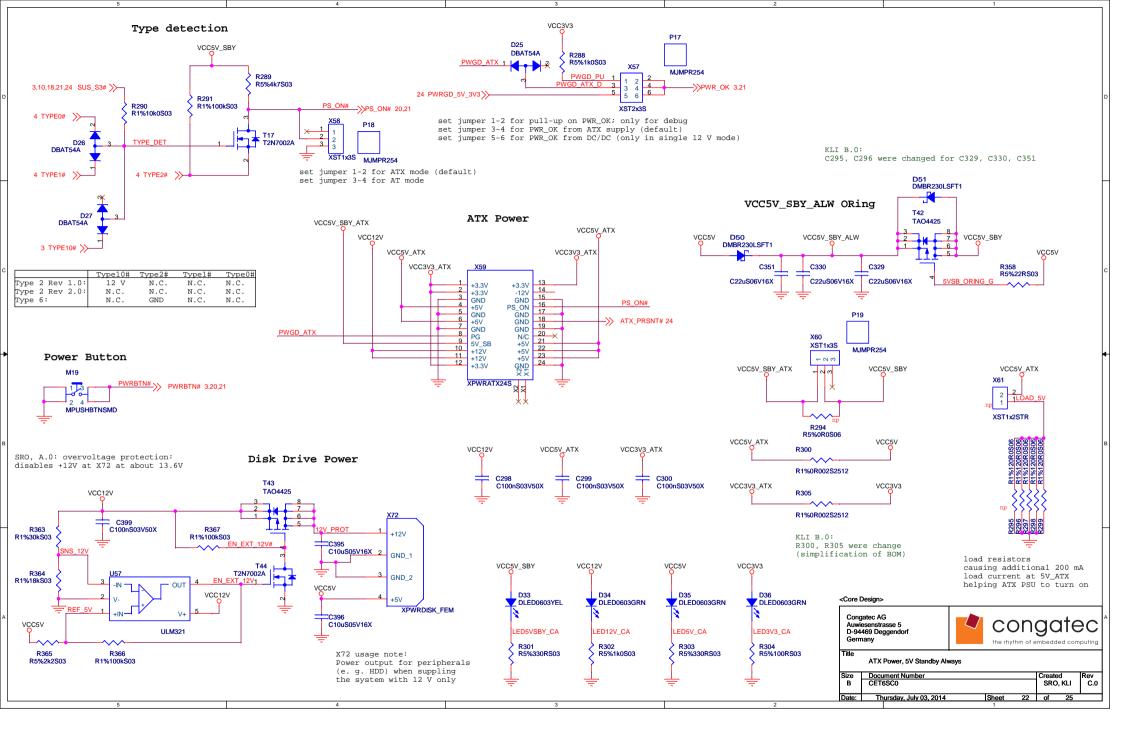


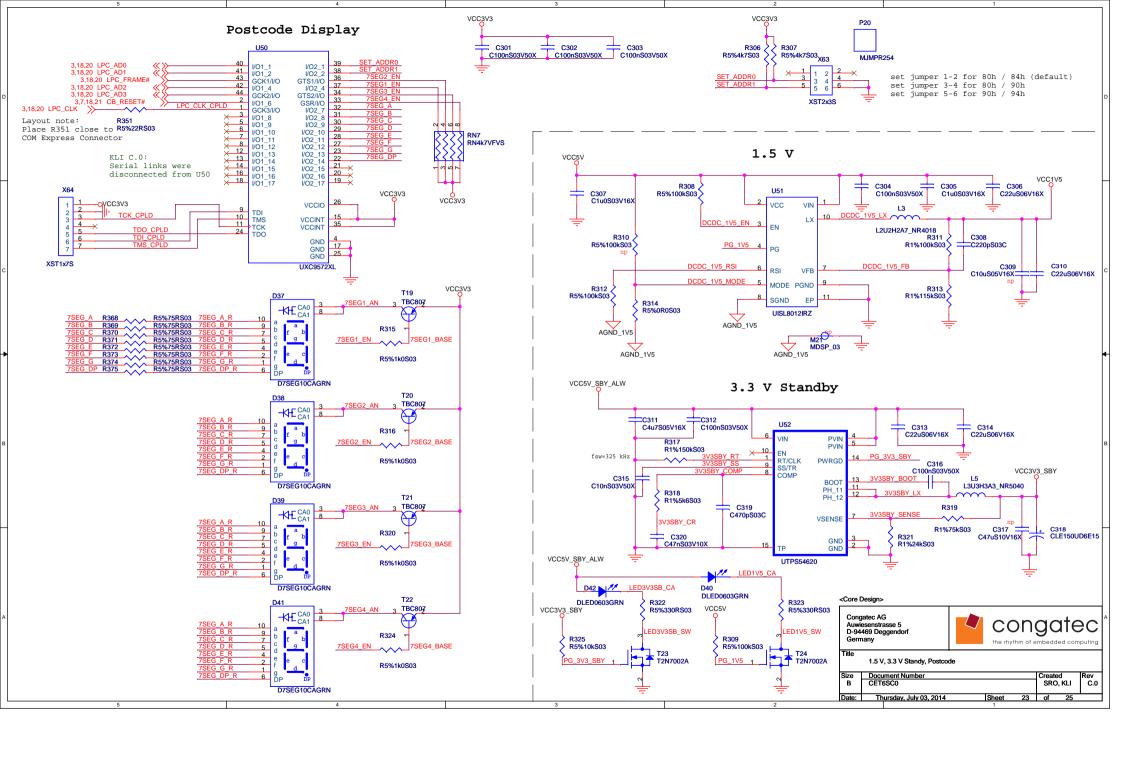


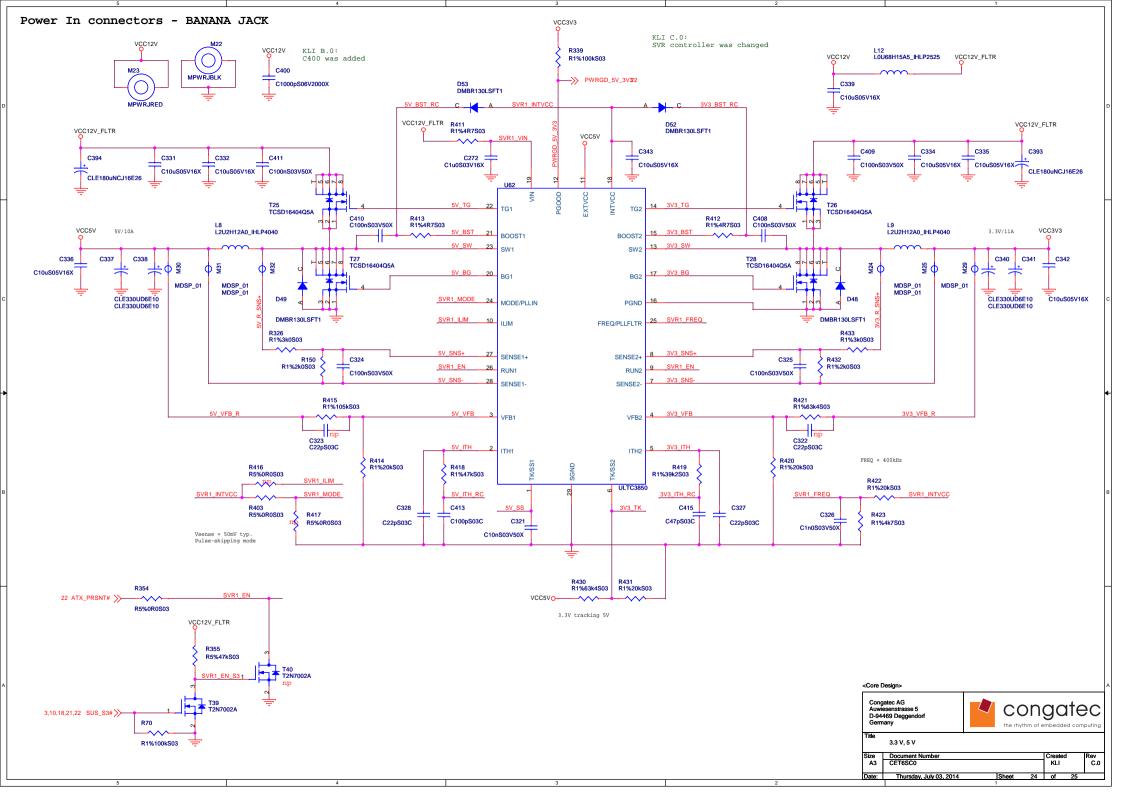












HISTORY 10.01.2011 design created SRO 19.08.2011 SRO page 3: set SUS S3# buffer to be populated page 4: swapped connection of DDI2_AUX, DDI3_AUX page 6: changed SHLDGND - GND connection page 7: exchanged UPI6C21200 by UICS9DB1233 (PCIe Gen. 3 compatible Clock Buffer) page 9: connected X12.B17, B31, B81 to B48, to enable PCIe RefClk also with x1, x4 and x16 cards page 11: exchanged SATA connectors page 13, 14: swapped connection of TMDS B CLK and TMDS C CLK at U29, U30, added circuitry to connect DDC-PU only in TMDS mode page 18: changed oscillator at Super I/O from 48 MHz to 24 MHz mirrored X42, X44 to be compatible to conga-adapPS2 page 19: connected U39.24, U39.25, U40.24, U40.25 to VCC5V to enable RS232 Levelshifter swapped DTR and TXD signals at X47, X62 to maintain compatibility to conga-CEVAL page 20: added PU at SPI_CS# to ensure stable level at SPI flash page 21: changed connection of X53.1 and X53.3 from 3.3V to 5V page 22: changed VCC5V SBY ALW Oring circuit added overvoltage protection circuit to Disk Drive Power Connector General: changed connection of I/O connector's shield from SHLDGND to GND General: changed CLE150UC6E25 to CLE150UD6E15 page 3: C389, C402, C403 were added. C385, C386 were changed from 0805 to 0603 (0805 too high to place under module). 7.8.2013 page 4: R398, R399, X75, X76 were added (power consumption measurement). C404 was added. C387, C388 were changed from 0805 to 0603. page 5: TPS2062 were changed for TPS2062C (previous chip has a bug). page 6: C24, C27 were changed from 100u (tantalum) to 150u (polymer). U16 was changed to a new type for better signal quality page 8, 9: C53, C59, C74, C76, C88, C100 were changed for 47u MLCC (recommended operating voltage for tantalum capacitors is 8V and they are sensitive for high ripple current, not recommended for 12V). page 11: VCC for U27 and U28 was changed from VCC3V3 to VCC3V3_SBY. SATA connectors were changed from TH to SMT type (X68-X71) for better signal integrity. page 12: AC coupling capacitors C370-C377 were changed from 0603 to 0402. C146, C151 were changed (new DC blocking capacitors for 12V). C153 was deleted. page 13, 14: SN75DP122 was changed for SN75DP126 (new type, higher bandwidth). page 15: New connection for X35.6, pin is connected to LVDS BKLT EN JP page 18: AUX FAN circuit was changed (new option for driving 3pin FAN by COMe module) page 19: FB75, FB80 were changed for 100R/1.7A page 20: SPI socket (U43) was changed for a different type. LPC header was added for different types of LPC devices. page 21: FAN2_SENSE signal was connected to D2. C401 and D28 were added. X77 was added for connection to a probe. page 22: C295, C296 (100u tantalum, 10u MLCC) were changed for C329, 330 and C351 (3x 22u MLCC) page 23: RN8, RN9 were changed for R368-R375 (from 150R to 75R) page 24: C400 was added (high voltage MLCC) 27.6.2014 page 6: C405 was added. page 7: R79 was changed to installed, R113 was changed to NP (PLL bandwidth of PCIe clock buffer is set to Low, better signal integrity). X79, R434-R437 were added for measuring PCIe CLK signal from COMe module. page 17: Connection of R210 was changed, R210 is connected to U36 pin 2 (signal HDA_RST#_CDC). page 18: Clock oscillator for Super I/O was changed. New oscillator can provide 24MHz or 48MHz (selectable by jumper). page 20: LPC header was changed for TPM header, requested to have the connector for TPM module from Fujitsu. page 21: Jumper X80 was added to have an option to disconnect RTC battery. page 23: SERO TX/RX and SER1 TX/RX were disconnected from U50 (not used by U50) page 24: SVR was changed, previous controller has output discharge (unwanted when using ATX PSU). ISL62392 was replaced by LTC3850.

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Title
History

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